

**REMARKS**

By this Amendment, claims 2, 3 and 5-10 are canceled, and claims 1 and 4 are amended. Accordingly, claims 1 and 4 are pending.

The Office rejects claims 1-10 under 35 U.S.C. §112, second paragraph, as indefinite. This rejection is moot with respect to canceled claims 2, 3 and 5-10 and is respectfully traversed with respect to the remaining claims:

Claim 1 is amended to clarify that the press head is a compression bonding head. It is respectfully submitted that the claims are not narrowed by such amendment.

Claim 4 is amended to correct the dependency in view of the renumbering of claims by the Office Action.

It is respectfully submitted that claims 1 and 4 fully comply with 35 U.S.C. §112. Accordingly, withdrawal of the rejection is respectfully requested.

The Office Action rejects claims 1-3 and 6-8 under 35 U.S.C. §102(b) over Yamanaka (U.S. Patent 5,662,763). This rejection is traversed with respect to claims 1 and 4, and is moot with respect to canceled claims 2, 3 and 5-10.

Claim 1 recites *inter alia* "an apparatus for mounting a plurality of semiconductor devices ... with a plurality of suction parts for sucking and holding pressing chips and said semiconductor devices thereon, wherein said suction parts are provided at the position respectively corresponding to said semiconductor devices". It is respectfully submitted that Yamanaka fails to disclose, teach or suggest these claimed features.

START Yamanaka discloses in column 4, lines 15-19, "a part indicated by reference numeral 10 is a mount head. The mount head 10 holds a semiconductor chip 1, and the chip 1 is pressed and mounted on a substrate 3." Therefore, Yamanaka discloses mounting a single semiconductor chip using the mount head 10. Accordingly, Yamanaka does not disclose "a plurality of suction parts for sucking and holding pressing chips and said

semiconductor devices," as recited in claim 1, and claim 1 is patentable over the cited reference.

Claims 1-10 are further rejected under 35 U.S.C. §102(e) over Sato (U.S. Patent 5,985,064). This rejection is traversed with respect to amended claims 1 and 4, and is moot with respect to canceled claims 2, 3 and 5-10.

As disclosed in Sato, column 2, lines 61-63, "a chip 1 is held by suction or vacuum on lower surfaces of nozzle 3 which is provided at a lower side of a nozzle holding portion 2." Therefore Sato, like Yamanaka, discloses a device for mounting only a single semiconductor chip. Nowhere in Sato is "a plurality of suction parts for sucking and holding pressing chips and said semiconductor devices," as recited in claim 1, disclosed.

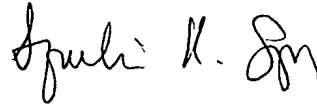
Therefore, claim 1 is patentable over Sato and Yamanaka. Applicant respectfully requests that the rejection of claim 1 under 35 U.S.C. §102(e) over Sato, and under 35 U.S.C. §102(b), over Yamanaka, be withdrawn.

Claim 4 depends from claim 1, and is patentable for the reasons set forth above, as well as for the additional features it recites.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1 and 4 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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Attachment:  
Petition for Extension of Time

Date: October 24, 2003

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